



System Features:

- World languages support
- Small footprint with built in high quality Windows® XP PC
- Multi-range test modules down to 1/10 of full scale
- 200kg die shear capacity
- One button microscope height adjustment
- Large stage travel for up to 300mm wafers or substrates
- Robust, guarded test modules
- Rich data export and analysis options
- Excel® compatible IBM Lotus Symphony office suite
- SQL database query editor built in
- Configurable user access permission levels
- Comfortable, ergonomic joystick controls
- Handles fine UFP geometries with pitch down to 20 microns
- High speed zone shear test of solder ball integrity
- Stud Pull capacity up to 200kgf
- Tweezer pull to support cavity and fine pitch geometries
- Precision Ball Pull (CBP) to support a range of BGA applications
- Die strength 3 point test for thin die evaluation

Royce Instruments, Inc.
500 Gateway Drive
Napa, California 94558, U.S.A.
(707) 255-9078
www.royceinstruments.com